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**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of: Isao OCHIAI

Group Art Unit: 2827

Serial No. 10/772,345

Examiner: Robert B. Davis

Filed: February 6, 2004

Attorney Docket No. 2905-107

Customer Number: 52190

For: **LEAD FRAME, RESIN SEALING MOLD AND METHOD FOR  
MANUFACTURING A SEMICONDUCTOR DEVICE USING THE SAME**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE**

Dear Sir:

In response to the Office Action of May 10, 2006, entry of the following amendments and remarks is most respectfully requested.

1. Amendments to the drawings begin at page 2;
2. Amendments to the claims begin at page 3;
3. Remarks begin at page 6.